AMENDMENTS

Amendments to the Claims:

Please cancel claims 108-134, 139, 140 and 144-146 without prejudice or disclaimer. Please enter new claims 147-184 as set forth in the complete listing of the claims hereafter. This complete listing of the claims replaces previous claim listings.

- 147 (New). A process for preparing a substrate having an array of spots having matrix for matrix-assisted laser-desorption ionization (MALDI) mass spectrometry and no analyte, which comprises:
 - (a) depositing a defined and controlled 0.2 to 20 nanoliter volume of a solution comprising 3-hydroxypicolinic acid matrix, an evaporating solvent and no analyte at a plurality of discrete locations on the surface of a substrate; and
 - (b) evaporating the solvent, thereby forming an array of spots on the surface of the substrate comprising the matrix and no analyte.
- 148 (New). The process of claim 147, wherein the substrate comprises material selected from the group consisting of silica, glass, cellulose, silicon, metal, plastic, polymer and metal-grafted polymer.
- 149 (New). The process of claim 147, wherein the substrate comprises a flat surface, a flat surface with pits, a solid or porous bead, a membrane or a pin.
- $\,$ 150 (New). The process of claim 147, wherein the substrate comprises a flat surface.
 - 151 (New). The process of claim 147, wherein the substrate comprises silicon.
 - 152 (New). The process of claim 147, wherein the substrate comprises a metal.
 - 153 (New). The process of claim 147, wherein the substrate comprises a plastic.
- 154 (New). The process of claim 147, wherein the substrate comprises a membrane
- 155 (New). The process of claim 147, wherein the substrate comprises a metal-grafted polymer.
- 156 (New). The process of claim 147, wherein the substrate is chemically functionalized

- 157 (New). The process of claim 147, wherein the substrate is chemically functionalized with beads.
- 158 (New). The process of claim 147, wherein the substrate is chemically functionalized with a dendritic material.
 - 159 (New). The process of claim 147, wherein the substrate is a chip.
 - 160 (New). The process of claim 147, wherein the substrate is a silicon chip.
 - 161 (New). The process of claim 147, wherein each spot is a flat disk.
- 162 (New). The process of claim 147, wherein the spot size is defined by square dimensions of 800 micrometers by 800 micrometers or less.
- 163 (New). The process of claim 147, wherein the spot size is defined by square dimensions of 450 micrometers by 450 micrometers or less.
- 164 (New). The process of claim 147, wherein each spot consists essentially of the matrix after the solvent has evaporated.
- 165 (New). The process of claim 147, wherein each spot consists of the matrix after the solvent has evaporated.
 - 166 (New). The process of claim 147, wherein the solvent comprises water.
 - 167 (New). The process of claim 166, wherein the solvent is water.
 - 168 (New). The process of claim 147, wherein the solvent comprises CH₃CN.
 - 169 (New). The process of claim 168, wherein the solvent is 50% CH₃CN.
- 170 (New). The process of claim 147, wherein the solution comprising the matrix consists essentially of the matrix and the evaporating solvent.
- 171 (New). The process of claim 147, wherein the solution comprising the matrix consists of the matrix and the evaporating solvent.
- 172 (New). The process of claim 147, wherein the solution comprising the matrix is a saturated matrix solution.
- 173 (New). The process of claim 147, wherein the solution comprising the matrix is a diluted matrix solution.
- 174 (New). The process of claim 147, wherein the solution is dispensed by an automated dispenser.

- 175 (New). The process of claim 147, wherein the automated dispenser comprises a vesicle having a chamber and a transducer element for ejecting fluid from the chamber.
- 176 (New). The process of claim 174, wherein the transducer element is selected from the group consisting of piezoelectric, electric, electrorestrictive, magnetorestrictive, electromechanical transducers and the like.
- 177 (New). The process of claim 175, wherein the transducer element is a piezoelectric transducer.
- 178 (New). The process of claim 147, wherein the automated dispenser deposits the solution without touching the surface of the substrate.
- 179 (New). The process of claim 147, wherein the automated dispenser comprises a vesicle that comprises an interior chamber suitable for carrying a solution.
- 180 (New). The process of claim 147, wherein the automated dispenser comprises a vesicle that comprises a pin having a chamber of sufficient narrow bore to allow the chamber to at least partially fill with a solution by capillary action.
- 181 (New). The process of claim 147, wherein the automated dispenser deposits the solution by contacting the surface of the substrate.
- 182 (New). The process of claim 147, wherein the automated dispenser comprises a vesicle that comprises a solid shaft of material.
- 183 (New). The process of claim 147, wherein the automated dispenser comprises a vesicle that is rastered over the surface of the substrate.
- 184 (New). The process of claim 147, wherein the automated dispenser comprises a plurality of vesicles in an array.